

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2238	(Cu or copper) same ("copper oxide" or "CuO.sub.2") same (etch\$5 or polish\$4 or planariz\$5)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 10:06
L3	198	(Cu or copper) same ("copper oxide" or "CuO.sub.2") same (etch\$5 or polish\$4 or planariz\$5) same (co or cobalt)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 10:04
L4	349	(Cu or copper) and ("copper oxide" or "CuO.sub.2") and (etch\$5 or polish\$4 or planariz\$5) and (co or cobalt) and (peroxide or glycine or oxidizer) and interconnect	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 10:05
L5	495	(Cu or copper) and ("copper oxide" or "CuO.sub.2") and (etch\$5 or polish\$4 or planariz\$5) and (co or cobalt) and (peroxide or glycine or oxidizer) and (interconnect or wiring)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 10:08
L6	1355	1 and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 10:06
L7	1528	((438/745) or (438/750) or (438/754)).CCLS.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/30 10:07
L8	57	1 and 7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/30 10:07

## EAST Search History

L9	476	(Cu or copper) and ("copper oxide" or "CuO.sub.2") and (etch\$5 or polish\$4 or planariz\$5) and (capping or barrier) and (peroxide or glycine or oxidizer) and (interconnect or wiring)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 10:08
L10	7	koos-daniel-a.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 10:08